

IN THE SPECIFICATION:

After the Title, please insert the following paragraph:

- - This application is a Continuation-In-Part of Application Serial No. 10/328,135, filed December 20, 2002, which issued as U.S. Patent Number 6,736,370. - -

Please amend Paragraph [0147], at page 57, lines 2 - 8 as follows:

- - [0147]     ~~The disclosure pertains to a~~ A space-conserving integrated fluid delivery system which is particularly useful for gas distribution in semiconductor processing equipment. The ~~present~~ invention also ~~pertains to~~ includes an integrated fluid flow network architecture, which may include, in addition to a layered substrate containing fluid flow channels, various fluid handling and monitoring components. The layered substrate is diffusion bonded, and the various fluid handling and monitoring components may be partially integrated or fully integrated into the substrate, depending on design and material requirements. - -